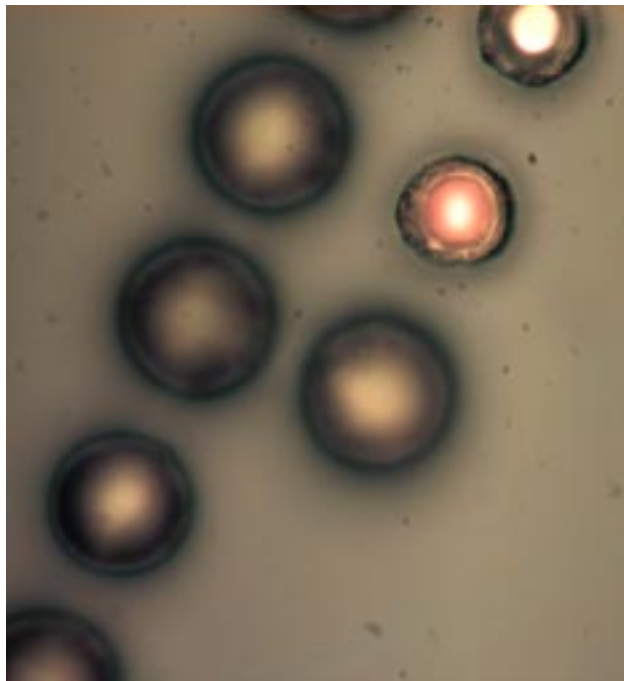
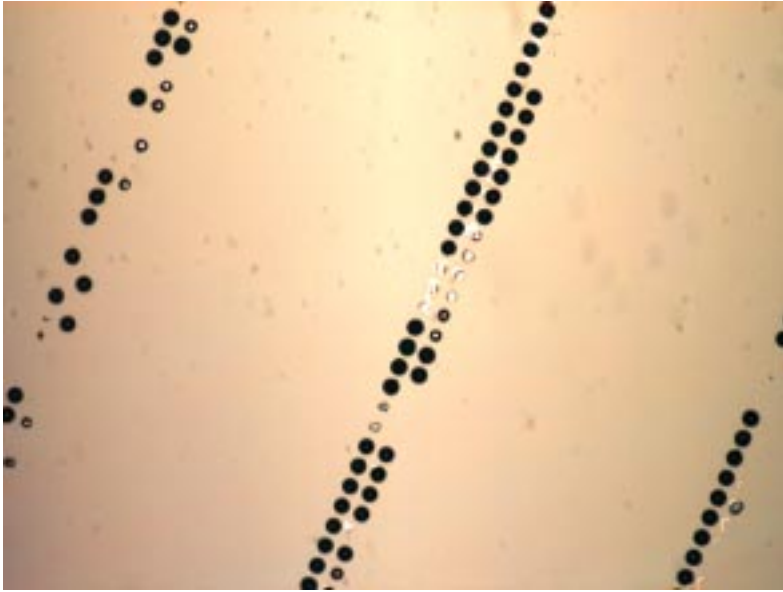


Dummy Wafer in June



Wafer cracked during grinding is claimed. Also broke piece during handling
Bumps removed - see pictures
No evidence of significant residual photoresist when washed one piece.
Tentative conclusion is that UV releasing tape grabbed photoresist and pulled most of it all along with some bumps and under bump metal